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Kind regards,

Team Nexperia

DATA SHEET

CBT16210
20-bit bus switch with 10-bit output enables

Product specification
Supersedes data of 2000 Sep 25

2000 Oct 12

Philips
Semiconductors

PHILIPS

20-bit bus switch with 10-bit output enables CBT16210

FEATURES

- 5Ω switch connection between two ports
- TTL compatible control input levels
- Package options include shrink small outline (SSOP) and thin shrink small outline (TSSOP)
- ESD exceeds: CDM 1000 V; HBM 2000 V

DESCRIPTION

The CBT16210 provides 20 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as a dual 10-bit bus switch with separate output-enable ($\overline{OE}$) inputs. It can be used as two 10-bit bus switches or as one 20-bit bus switch. When $\overline{OE}$ is low, the associated 10-bit bus switch is on, and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, and a high-impedance state exists between the ports.

The CBT16210 is characterized for operation from –40°C to +85°C.

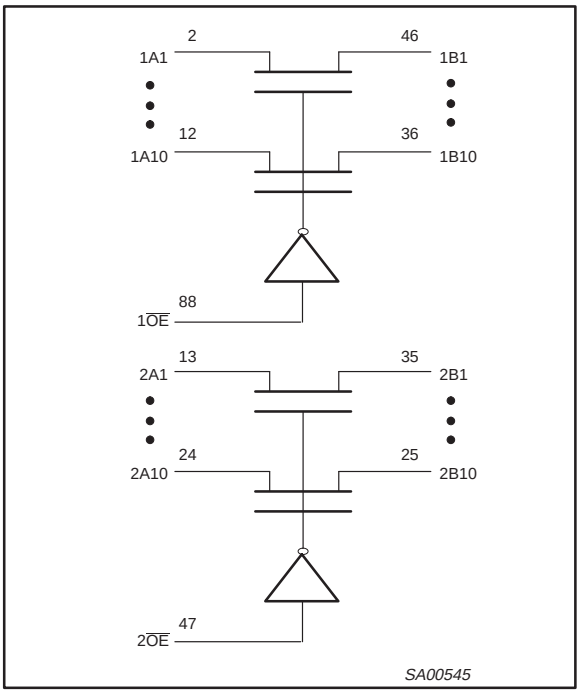
QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T_{amb} = 25°C; GND = 0V	TYPICAL	UNIT
t_{PLH} t_{PHL}	Propagation delay An to Yn	C_L = 50pF; V_{CC} = 5V	0.25	ns
C_{IN}	Input capacitance	V_I = 0V or V_{CC}	4.3	pF
C_{OUT}	Output capacitance	Outputs disabled; V_O = 0V or V_{CC}	6.9	pF
I_{CCZ}	Total supply current	Outputs disabled; V_{CC} = 5.5V	4.0	µA

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	ORDER CODE	DWG NUMBER
48-Pin Plastic SSOP Type III	–40°C to +85°C	CBT16210 DL	SOT370-1
48-Pin Plastic TSSOP Type II	–40°C to +85°C	CBT16210 DGG	SOT362-1

LOGIC SYMBOL

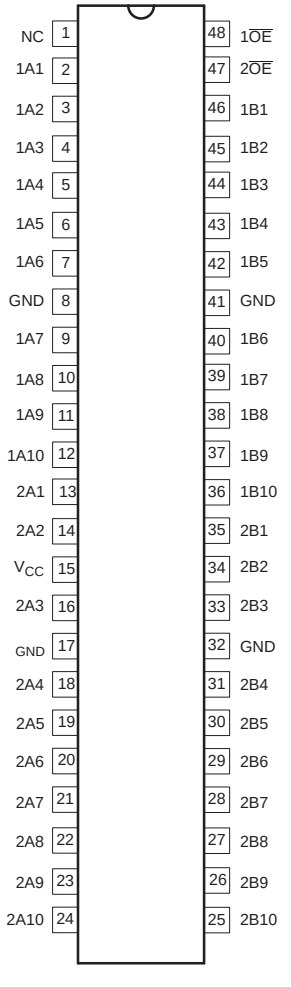


FUNCTION TABLE

INPUTS		OUTPUTS	
$1\overline{OE}$	$2\overline{OE}$	1A, 1B	2A, 2B
L	L	1A = 1B	2A = 2B
L	H	1A = 1B	Z
H	L	Z	2A = 2B
H	H	Z	Z

H = High voltage level
L = Low voltage level
Z = High impedance "off" state

PIN CONFIGURATION



PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1	NC	No internal connection
48, 47	$1\overline{OE}$, $2\overline{OE}$	Output enables
2, 3, 4, 5, 6, 7, 9, 10, 11, 12	1A1-1A10	Inputs
46, 45, 44, 43, 42, 40, 39, 38, 37, 36	1B1-1B10	Outputs
13, 14, 16, 18, 19, 20, 21, 22, 23, 24	2A1-2A10	Inputs
35, 34, 33, 31, 30, 29, 28, 27, 26, 25	2B1-2B10	Outputs
8, 17, 32, 41	GND	Ground (0V)
15	V_{CC}	Positive supply voltage

ABSOLUTE MAXIMUM RATINGS[1, 2]

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		–0.5 to +7.0	V
I_{IK}	DC input diode current	$V_I < 0$	–50	mA
V_I	DC input voltage[3]		–0.5 to +7.0	V
V_{OUT}	DC output voltage[3]	output in Off or High state	–0.5 to +5.5	V
I_{OUT}	DC output current	output in Low state	128	mA
T_{stg}	Storage temperature range		–65 to 150	°C

NOTES:
1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS		UNIT
		Min	Max	
V_{CC}	DC supply voltage	4.5	5.5	V
V_{IH}	High-level input voltage	2.0		V
V_{IL}	Low-level Input voltage		0.8	V
T_{amb}	Operating free-air temperature range	–40	+85	°C

DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			T_{amb} = –40°C to +85°C			
			Min	Typ[1]	Max	
V_{IK}	Input clamp voltage	V_{CC} = 4.5 V; I_I = –18 mA			–1.2	V
V_P	Output high pass voltage	$V_{in} – V_{cc}$ = 5.0 V, I_{OUT} = –100 µA	3.4	3.6	3.9	V
I_I	Input leakage current	V_{CC} = 0 V; V_I = 5.5 V			10	µA
		V_{CC} = 5.5 V; V_I = GND or 5.5 V			±1	
I_{CC}	Quiescent supply current[2]	V_{CC} = 5.5 V; I_O = 0, V_I = V_{CC} or GND; $1\overline{OE}$=$2\overline{OE}$=GND			20	µA
ΔI_{CC}	Additional supply current per input pin[2]	V_{CC} = 5.5 V, one input at 3.4 V, other inputs at V_{CC} or GND			2.5	mA
C_I	Control pins	V_I= 3 V or 0		4.5		pF
$C_{IO(OFF)}$	Port capacitance in off state	V_O = 3 V or 0, $\overline{OE}$ = V_{CC}		6.9		pF
r_{on}[3]		V_{CC} = 4.5 V; V_1 = 0 V; I_I = 64 mA		5	7	Ω
		V_{CC} = 4.5 V; V_1 = 0 V; I_I = 30 mA		5	7	
		V_{CC} = 4.5 V; V_1 = 2.4 V; I_I = –15 mA		10	15	

NOTES:
1. All typical values are at V_{CC} = 5 V, T_{amb} = 25°C
2. This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND
3. Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

AC CHARACTERISTICS

GND = 0 V; t_R; C_L = 50 pF

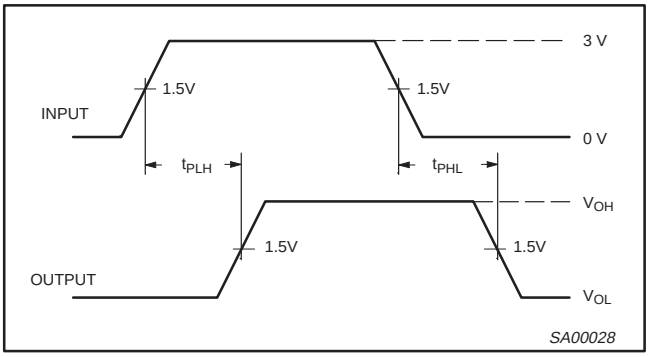
SYMBOL	PARAMETER DESCRIPTION	LIMITS –40°C to +85°C V_{CC} = 5 V ± 0.5 V			UNITS
		Min	Mean	Max	
t_{pd}	Propagation delay[1]			250	ps
t_{PZH}	Output enable time to HIGH level	1.5	3.3	5.0	ns
t_{PHZ}	Output disable time from HIGH level	1.0	2.4	4.5	ns
t_{PZL}	Output enable time to LOW level	1.5	4.0	6.5	ns
t_{PLZ}	Output disable time from LOW level	1.5	3.8	6.0	ns

NOTES:

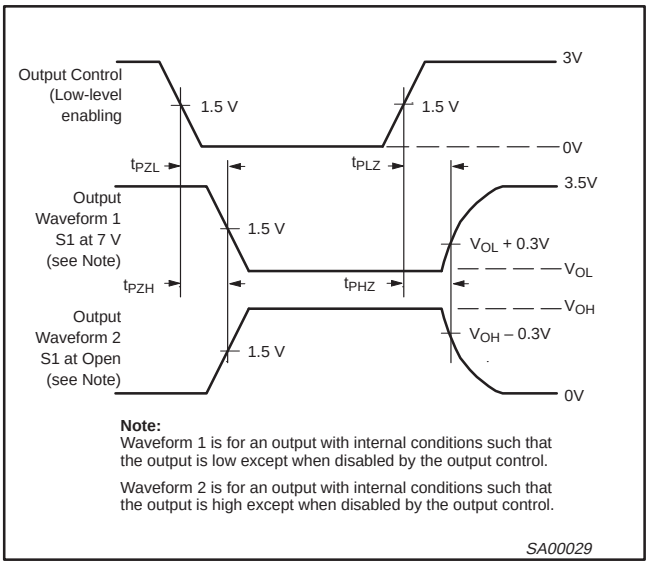
1. This parameter is warranted but not production tested. The propagation delay is based on the RC time constant of the typical on-state resistance of the switch and a load capacitance of 50 pF, when driven by an ideal voltage source (zero output impedance).

AC WAVEFORMS

V_M = 1.5 V, V_{IN} = GND to 3.0 V

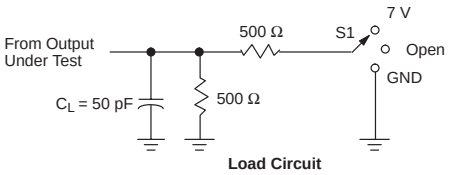


Waveform 1. Input (An) to Output (Yn) Propagation Delays



Waveform 2. 3-State Output Enable and Disable Times

TEST CIRCUIT AND WAVEFORMS



Load Circuit

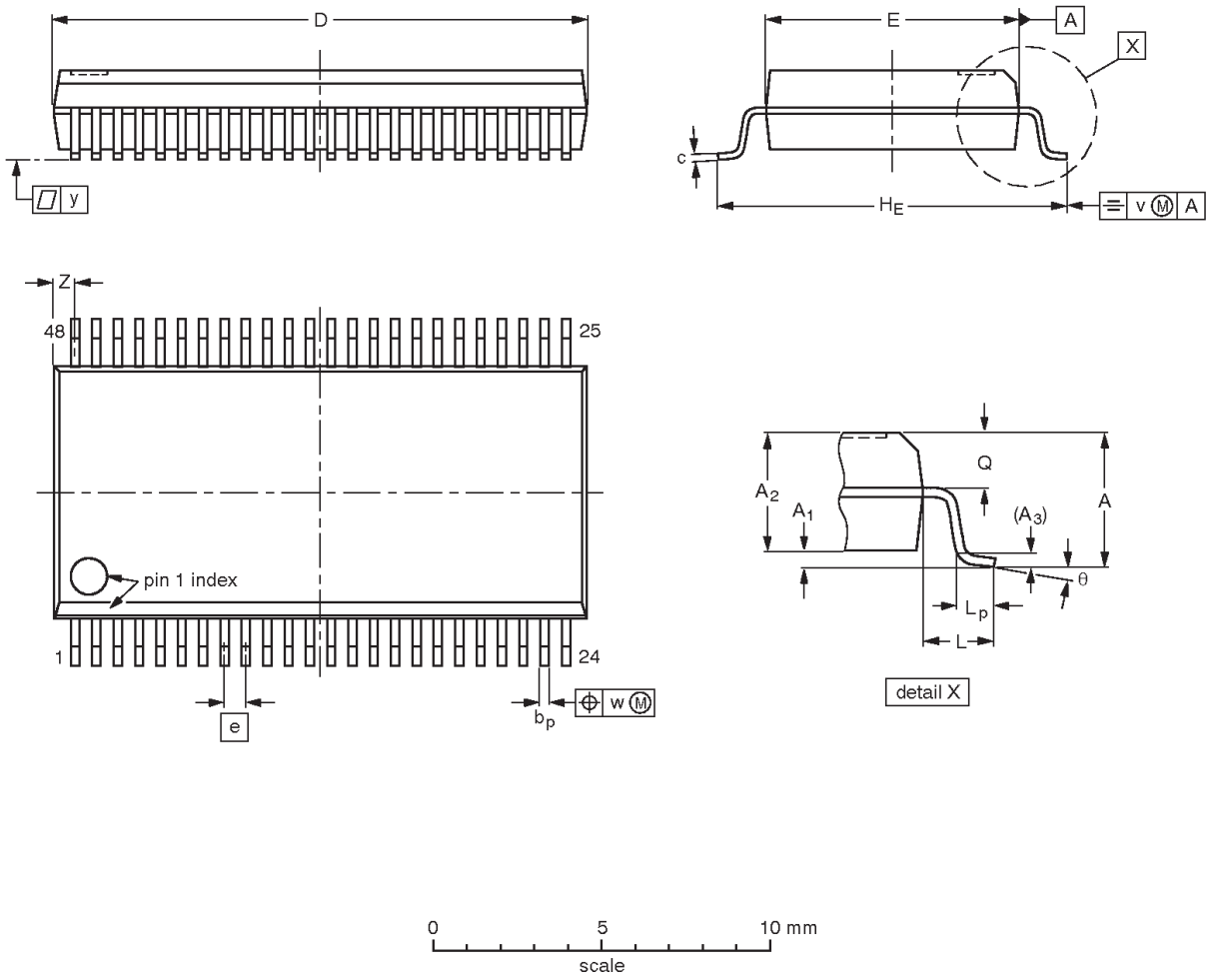
TEST	S1
t_{pd}	open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	open

DEFINITIONS

C_L = Load capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.

SA00012

SSOP48: plastic shrink small outline package; 48 leads; body width 7.5 mm **SOT370-1**



DIMENSIONS (mm are the original dimensions)

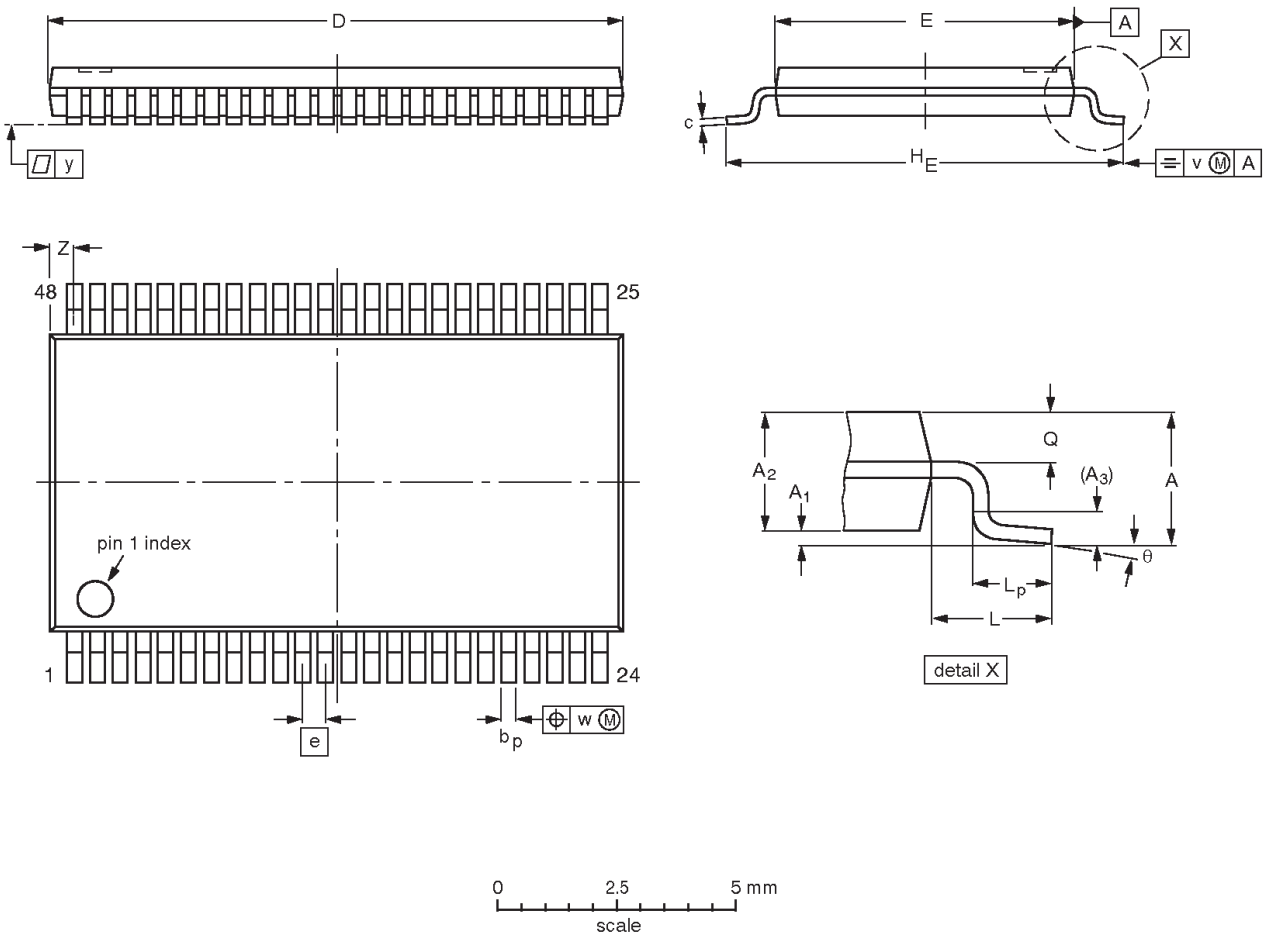
UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	16.00 15.75	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT370-1		MO-118				~~95-02-04~~ 99-12-27

TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1 mm **SOT362-1**



DIMENSIONS (mm are the original dimensions).

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	Z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	12.6 12.4	6.2 6.0	0.5	8.3 7.9	1	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.8 0.4	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES					EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ				
SOT362-1		MO-153					~~95-02-10~~ 99-12-27

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
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[1] Please consult the most recently issued datasheet before initiating or completing a design.

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